

# Lab 2B switch characterization

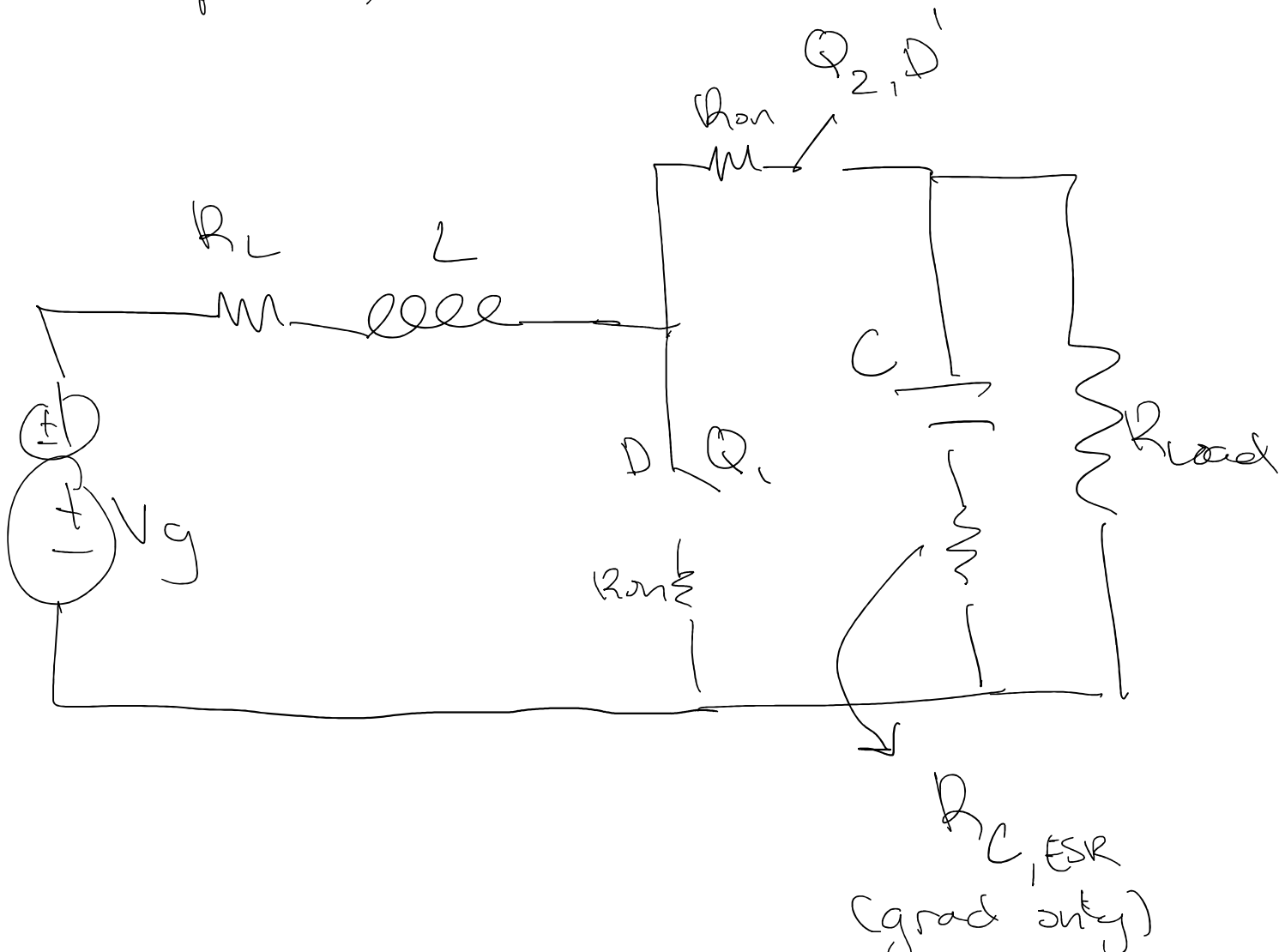
Wednesday, November 3, 2021 11:30 PM

## Logistics:

- 1) Lab 1 due soon! Ping me with any questions
- 2) No Lab 11/11 (Veteran's day)

## Lab 2B:

Solve this model:  
(and please)



(grad inty)

- mostly analytical

- part (a) :

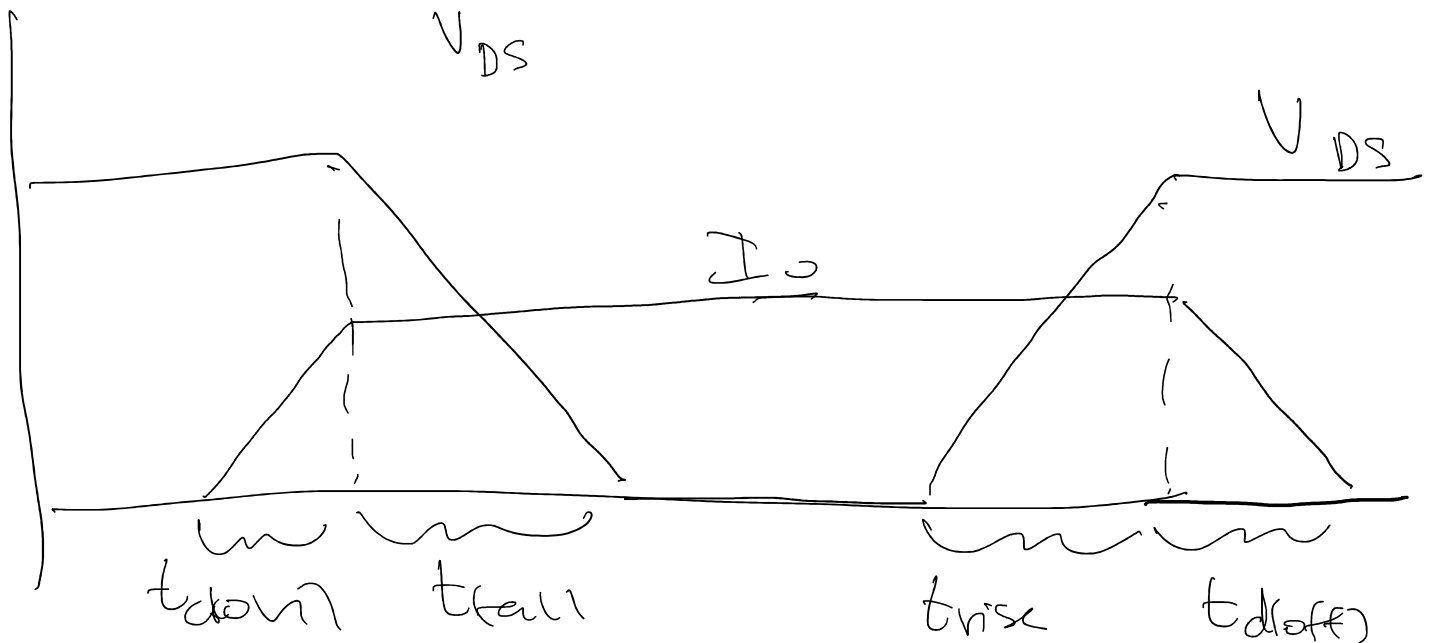
(1) find  $\frac{V}{V_g}$  using balance equations. Just like (tw)!

(2) find  $I$  equation using current ripple equation

(3) conduction loss as usual ( $R_{on}$  in datasheet)

switching loss:

- disregard  $R_{on}$  when finding  $V_{DS}$



$$E_{on} = \frac{1}{2} V_d I_D t_{on}$$

$$t_{on} = t_{down} + t_{fall}$$

$$E_{off} = \frac{1}{2} V_d I_D t_{off}$$

$$t_{off} = t_{d_{off}} + t_{rise}$$

$$E_{loss} = E_{on} + E_{off}$$



find in  
datasheet

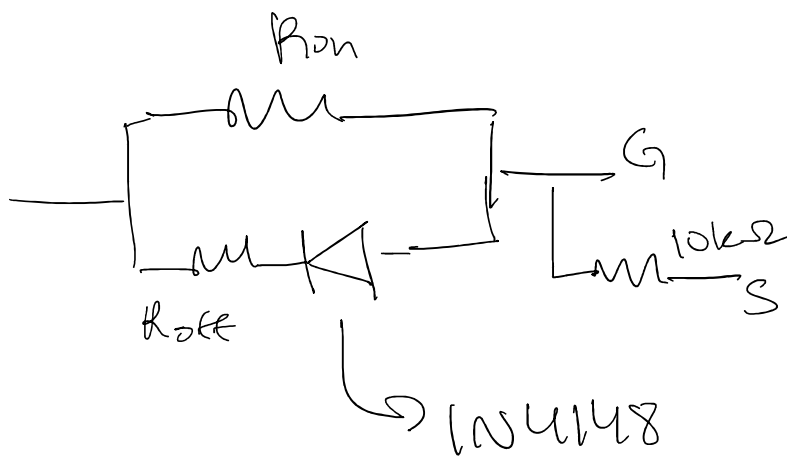
$$P_{loss} = E_{loss} f_{sw}$$

c4) : efficiency :  $\eta$

$$P_{in} = P_{out} + P_{loss}$$

What is  $\eta$ ?

MOSFET  $R_{on} / R_{off}$



$R_{as}$  forces cutoff region when not driven

$R_{on} / R_{off}$  to prevent ringing

Suggest

$$R_{on} = 8 \Omega$$

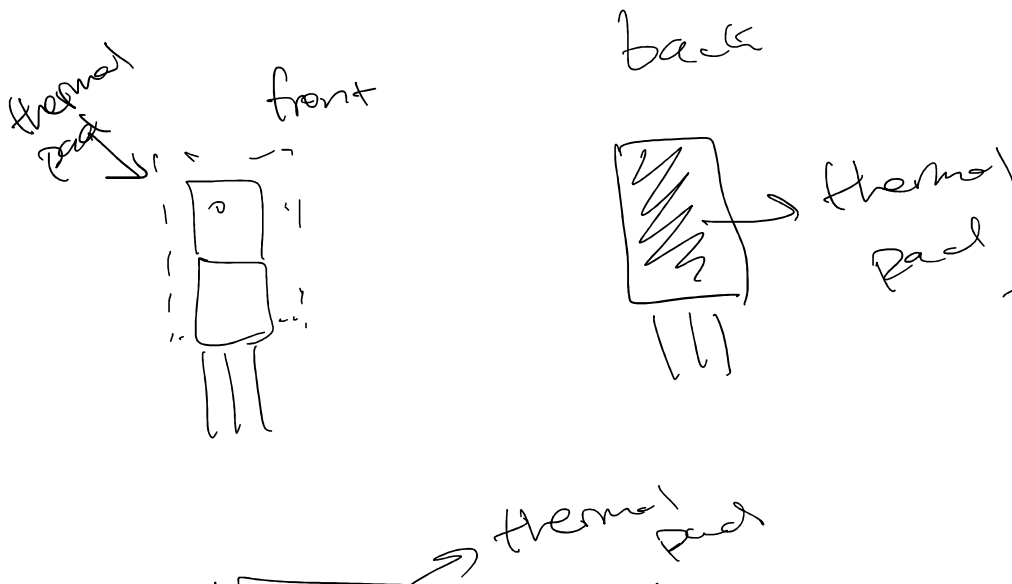
$$R_{eff} = 10 \Omega$$

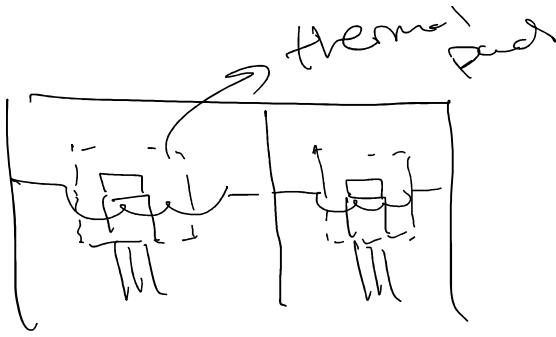
$$R_{off} > R_{on}$$

info in UCC 27712

(out of scope)

MOSFET HEASINK w/ Thermal Pads





- stick thermal pad adhesive side to back of MOSFET
- thermal pad BETWEEN heat sink and MOSFET.